

**Clean version of all pending claims**

1. (Amended once) An apparatus comprising:  
  
a bond wire;  
  
an insulating material coating said bond wire, the insulating material having a thickness in the range of approximately 0.2 micrometers to approximately 0.6 micrometers; and  
  
a first end of said bond wire connected to a bond pad.
2. (Amended twice) The apparatus of claim 1 wherein said bond wire material is selected from a group consisting of gold, silver, aluminum, and copper.
3. The insulated bond wire of claim 1 wherein said insulating material is comprised of a polymer.
5. (Amended once) The apparatus of claim 1 wherein said bond wire is connected to said bond pad through an ultrasonic bond.
6. (Amended once) The apparatus of claim 1 further comprising said bond pad connected to an integrated circuit.

7. (Amended once) The apparatus of claim 1 further comprising said bond pad connected to a substrate.
8. (Amended twice) An integrated circuit comprising:
  - a first bond wire;
  - an insulating material coating said first bond wire;
  - a first end of said first bond wire connected to a bond pad by ultrasonic bonding without previously removing the insulating material from the first end; and
  - a second bond wire crossing said first bond wire.
9. (Amended once) The integrated circuit of claim 8 further comprising an insulating material coating said second bond wire.
10. The pair of bond wires of claim 8 wherein said first bond wire touches said second bond wire.
11. (Cancelled)
12. (Amended twice) An integrated circuit assembly comprising:
  - an integrated circuit;

Attorney Docket No. 42390P10075

a substrate;

a bond wire connected to said integrated circuit and said substrate; and

a polymer insulating material coating said bond wire;

wherein said substrate is selected from a group consisting of aluminum lead frames and fine pitch ball grid arrays.

14. (Amended twice) An integrated circuit assembly comprising:

an integrated circuit;

a substrate;

a bond wire connected to said integrated circuit and said substrate; and

a polymer insulating material coating said bond wire;

wherein said bond wire material comprises silver.

15. (Amended twice) An integrated circuit assembly comprising:

an integrated circuit;

a substrate;

a bond wire connected to said integrated circuit and said substrate; and

an insulating material coating said bond wire to a thickness of between about .2 micrometers and about .6 micrometers.